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Understanding Embedded - FPGAs (Field Programmable Gate Array)

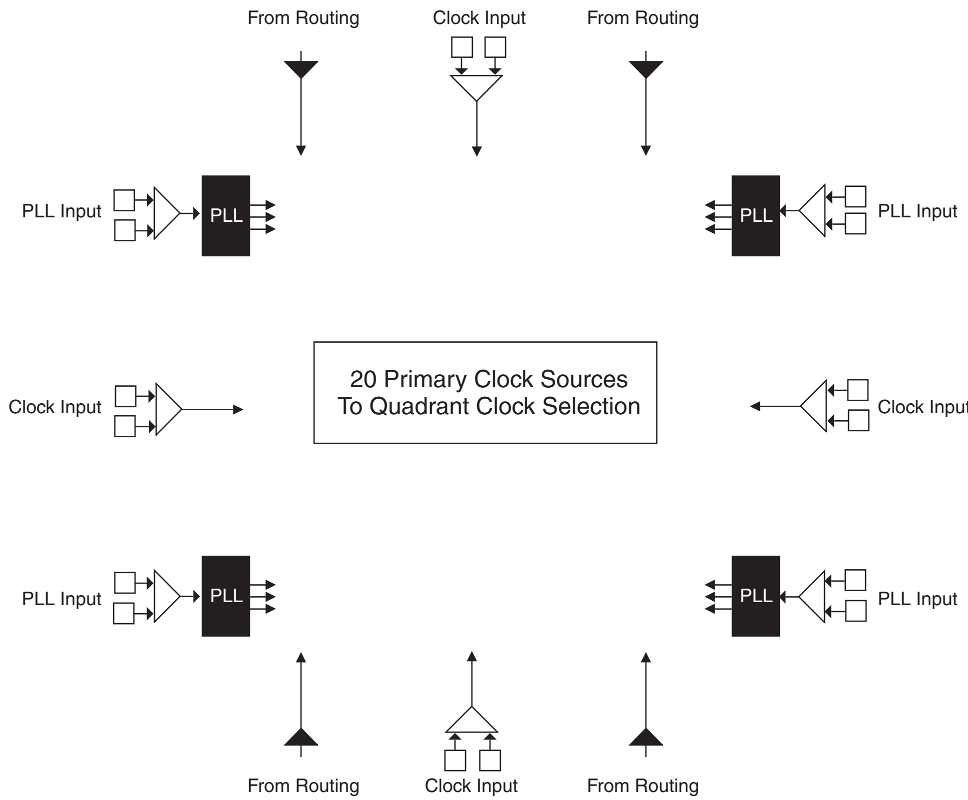
Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications,

Details	
Product Status	Obsolete
Number of LABs/CLBs	-
Number of Logic Elements/Cells	15000
Total RAM Bits	331776
Number of I/O	268
Number of Gates	-
Voltage - Supply	1.71V ~ 3.465V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	388-BBGA
Supplier Device Package	388-FPBGA (23x23)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfxp15c-4fn388c

Figure 2-5. Primary Clock Sources

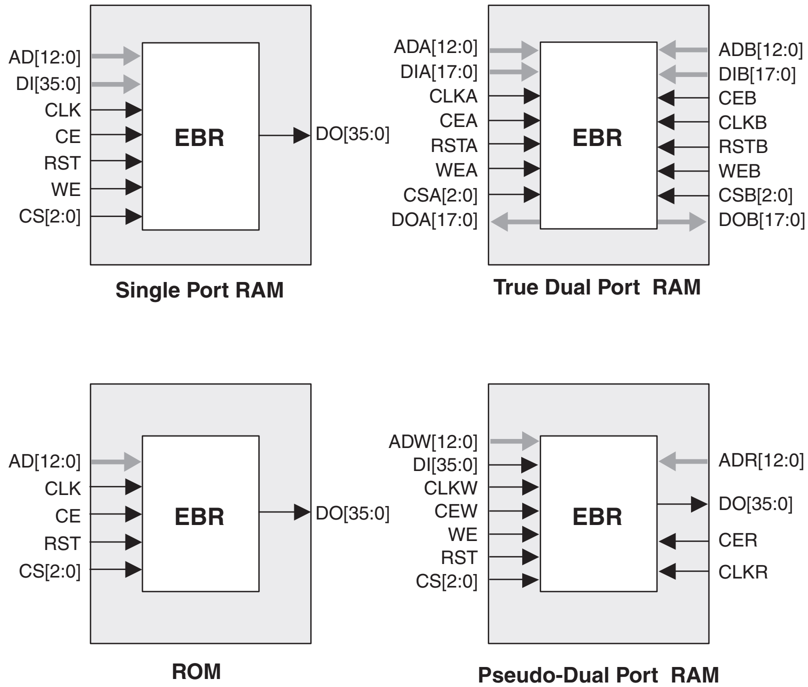


Note: Smaller devices have two PLLs.

Secondary Clock Sources

LatticeXP devices have four secondary clock resources per quadrant. The secondary clock branches are tapped at every PFU. These secondary clock networks can also be used for controls and high fanout data. These secondary clocks are derived from four clock input pads and 16 routing signals as shown in Figure 2-6.

Figure 2-14. sysMEM Memory Primitives



The EBR memory supports three forms of write behavior for single port or dual port operation:

1. **Normal** – data on the output appears only during read cycle. During a write cycle, the data (at the current address) does not appear on the output. This mode is supported for all data widths.

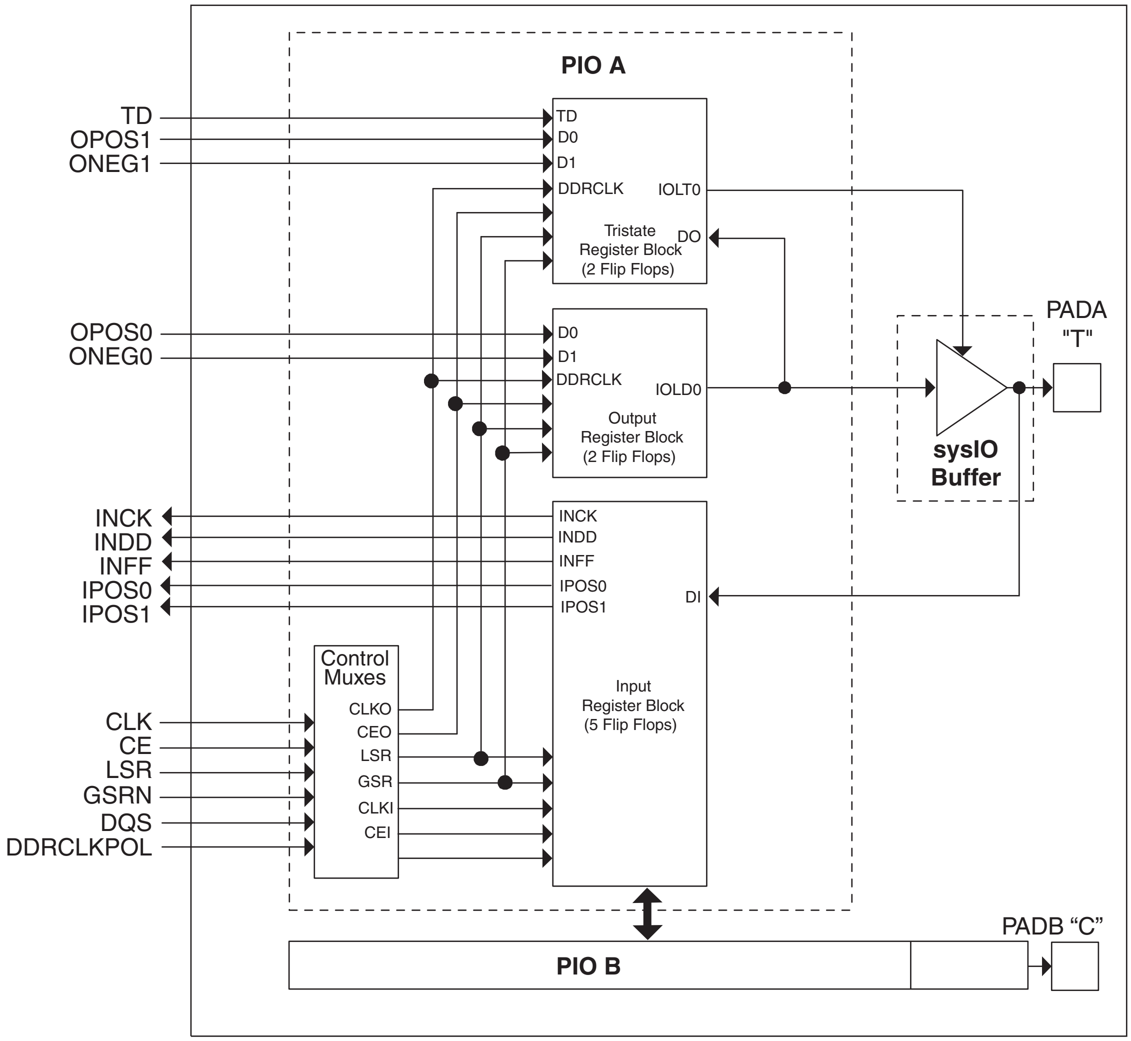
2. **Write Through** -þa copy of the input data appears at the output of the same port during a write cycle.þThis mode is supported for all data widths.

3. **Read-Before-Write** – when new data is being written, the old content of the address appears at the output. This mode is supported for x9, x18 and x36 data widths.

Memory Core Reset

The memory array in the EBR utilizes latches at the A and B output ports. These latches can be reset asynchronously. RSTA and RSTB are local signals, which reset the output latches associated with Port A and Port B respectively. The Global Reset (GSRN) signal resets both ports. The output data latches and associated resets for both ports are as shown in Figure 2-15.

Figure 2-17. PIC Diagram



In the LatticeXP family, seven PIOs or four (3.5) PICs are grouped together to provide two LVDS differential pairs, one PIC pair and one single I/O, as shown in Figure 2-18.

Two adjacent PIOs can be joined to provide a differential I/O pair (labeled as “T” and “C”). The PAD Labels “T” and “C” distinguish the two PIOs. Only the PIO pairs on the left and right edges of the device can be configured as LVDS transmit/receive pairs.

One of every 14 PIOs (a group of 8 PICs) contains a delay element to facilitate the generation of DQS signals as shown in Figure 2-19. The DQS signal feeds the DQS bus which spans the set of 13 PIOs (8 PICs). The DQS signal from the bus is used to strobe the DDR data from the memory into input register blocks. This interface is designed for memories that support one DQS strobe per eight bits of data.

The exact DQS pins are shown in a dual function in the Logic Signal Connections table in this data sheet. Additional detail is provided in the Signal Descriptions table in this data sheet.

in selected blocks the input to the DQS delay block. If one of the bypass options is not chosen, the signal first passes through an optional delay block. This delay, if selected, ensures no positive input-register hold-time requirement when using a global clock.

The input block allows two modes of operation. In the single data rate (SDR) the data is registered, by one of the registers in the single data rate sync register block, with the system clock. In the DDR Mode two registers are used to sample the data on the positive and negative edges of the DQS signal creating two data streams, D0 and D2. These two data streams are synchronized with the system clock before entering the core. Further discussion on this topic is in the DDR Memory section of this data sheet.

Figure 2-21 shows the input register waveforms for DDR operation and Figure 2-22 shows the design tool primitives. The SDR/SYNC registers have reset and clock enable available.

The signal DDRCLKPOL controls the polarity of the clock used in the synchronization registers. It ensures adequate timing when data is transferred from the DQS to the system clock domain. For further discussion of this topic, see the DDR memory section of this data sheet.

Figure 2-20. Input Register Diagram

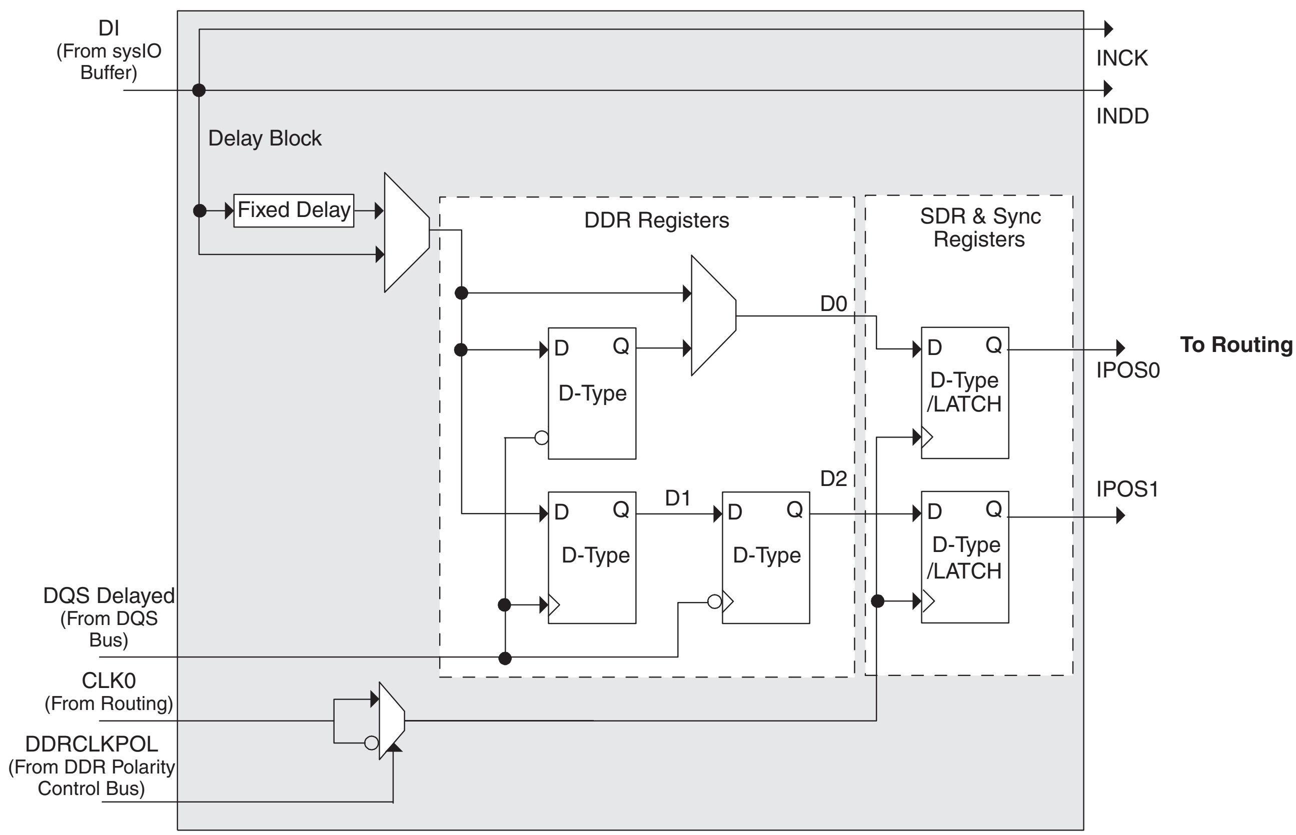


Table 2-8. Supported Output Standards

Output Standard	Drive	V_{CCIO} (Nom.)
Single-ended Interfaces		
LVTTL	4mA, 8mA, 12mA, 16mA, 20mA	3.3
LVCMOS33	4mA, 8mA, 12mA 16mA, 20mA	3.3
LVCMOS25	4mA, 8mA, 12mA 16mA, 20mA	2.5
LVCMOS18	4mA, 8mA, 12mA 16mA	1.8
LVCMOS15	4mA, 8mA	1.5
LVCMOS12	2mA, 6mA	1.2
LVCMOS33, Open Drain	4mA, 8mA, 12mA 16mA, 20mA	—
LVCMOS25, Open Drain	4mA, 8mA, 12mA 16mA, 20mA	—
LVCMOS18, Open Drain	4mA, 8mA, 12mA 16mA	—
LVCMOS15, Open Drain	4mA, 8mA	—
LVCMOS12, Open Drain	2mA. 6mA	—
PCI33	N/A	3.3
HSTL18 Class I, II, III	N/A	1.8
HSTL15 Class I, III	N/A	1.5
SSTL3 Class I, II	N/A	3.3
SSTL2 Class I, II	N/A	2.5
SSTL18 Class I	N/A	1.8
Differential Interfaces		
Differential SSTL3, Class I, II	N/A	3.3
Differential SSTL2, Class I, II	N/A	2.5
Differential SSTL18, Class I	N/A	1.8
Differential HSTL18, Class I, II, III	N/A	1.8
Differential HSTL15, Class I, III	N/A	1.5
LVDS	N/A	2.5
BLVDS[1]	N/A	2.5
LVPECL[1]	N/A	3.3

1. Emulated with external resistors.

Hot Socketing

The LatticeXP devices have been carefully designed to ensure predictable behavior during power-up and power-down. Power supplies can be sequenced in any order. During power up and power-down sequences, the I/Os remain in tristate until the power supply voltage is high enough to ensure reliable operation. In addition, leakage into I/O pins is controlled to within specified limits, which allows easy integration with the rest of the system. These capabilities make the LatticeXP ideal for many multiple power supply and hot-swap applications.

Sleep Mode

The LatticeXP "C" devices (V_{CC} = 1.8/2.5/3.3V) have a sleep mode that allows standby current to be reduced by up to three orders of magnitude during periods of system inactivity. Entry and exit to Sleep Mode is controlled by the SLEEPN pin.

During Sleep Mode, the FPGA logic is non-operational, registers and EBR contents are not maintained and I/Os are tri-stated. Do not enter Sleep Mode during device programming or configuration operation. In Sleep Mode, power supplies can be maintained in their normal operating range, eliminating the need for external switching of power supplies. Table 2-9 compares the characteristics of Normal, Off and Sleep Modes.

Figure 2-29 provides a pictorial representation of the different programming ports and modes available in the LatticeXP devices.

On power-up, the FPGA SRAM is ready to be configured with the sysCONFIG port active. The IEEE 1149.1 serial mode can be activated any time after power-up by sending the appropriate command through the TAP port.

Leave Alone I/O

When using 1532 mode for non-volatile memory programming, users may specify I/Os as high, low, tristated or held at current value. This provides excellent flexibility for implementing systems where reprogramming occurs on-the-fly.

TransFR (Transparent Field Reconfiguration)

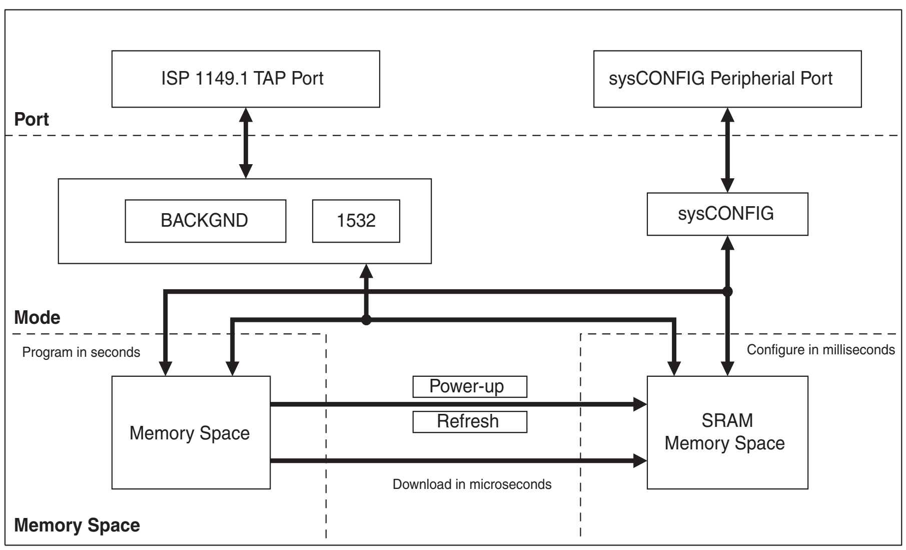
TransFR (TFR) is a unique Lattice technology that allows users to update their logic in the field without interrupting system operation using a single ispVM command. See Lattice technical note #TN1087, *Minimizing System Interruption During Configuration Using TransFR Technology,* for details.

Security

The LatticeXP devices contain security bits that, when set, prevent the readback of the SRAM configuration and non-volatile memory spaces. Once set, the only way to clear security bits is to erase the memory space.

For more information on device configuration, please see details of additional technical documentation at the end of this data sheet.

Figure 2-29. ispXP Block Diagram



Internal Logic Analyzer Capability (ispTRACY)

All LatticeXP devices support an internal logic analyzer diagnostic feature. The diagnostic features provide capabilities similar to an external logic analyzer, such as programmable event and trigger condition and deep trace memory. This feature is enabled by Lattice's ispTRACY. The ispTRACY utility is added into the user design at compile time.

For more information on ispTRACY, please see information regarding additional technical documentation at the end of this data sheet.

Oscillator

Every LatticeXP device has an internal CMOS oscillator which is used to derive a master serial clock for configuration. The oscillator and the master serial clock run continuously in the configuration mode. The default value of the

sysIO Recommended Operating Conditions

Standard	V_{CCIO}			V_{REF} (V)		
	Min.	Typ.	Max.	Min.	Typ.	Max.
LVCMOS 3.3	3.135	3.3	3.465	—	—	—
LVCMOS 2.5	2.375	2.5	2.625	—	—	—
LVCMOS 1.8	1.71	1.8	1.89	—	—	—
LVCMOS 1.5	1.425	1.5	1.575	—	—	—
LVCMOS 1.2	1.14	1.2	1.26	—	—	—
LVTTL	3.135	3.3	3.465	—	—	—
PCI33	3.135	3.3	3.465	—	—	—
SSTL18 Class I	1.71	1.8	1.89	0.833	0.9	0.969
SSTL2 Class I, II	2.375	2.5	2.625	1.15	1.25	1.35
SSTL3 Class I, II	3.135	3.3	3.465	1.3	1.5	1.7
HSTL15 Class I	1.425	1.5	1.575	0.68	0.75	0.9
HSTL15 Class III	1.425	1.5	1.575	—	0.9	—
HSTL 18 Class I, II	1.71	1.8	1.89	—	0.9	—
HSTL 18 Class III	1.71	1.8	1.89	—	1.08	—
LVDS	2.375	2.5	2.625	—	—	—
LVPECL[1]	3.135	3.3	3.465	—	—	—
BLVDS[1]	2.375	2.5	2.625	—	—	—

1. Inputs on chip. Outputs are implemented with the addition of external resistors.

sysIO Differential Electrical Characteristics

LVDS

Over Recommended Operating Conditions

Parameter Symbol	Parameter Description	Test Conditions	Min.	Typ.	Max.	Units
V_{INP}, V_{INM}	Input Voltage		0	—	2.4	V
V_{THD}	Differential Input Threshold		+/-100	—	—	mV
V_{CM}	Input Common Mode Voltage	100mV $\leq V_{THD}$	$V_{THD}/2$	1.2	1.8	V
		200mV $\leq V_{THD}$	$V_{THD}/2$	1.2	1.9	V
		350mV $\leq V_{THD}$	$V_{THD}/2$	1.2	2.0	V
I_{IN}	Input current	Power on or power off	—	—	+/-10	µA
V_{OH}	Output high voltage for V_{OP} or V_{OM}	R_T = 100 ohms	—	1.38	1.60	V
V_{OL}	Output low voltage for V_{OP} or V_{OM}	R_T = 100 ohms	0.9V	1.03	—	V
V_{OD}	Output voltage differential	(V_{OP} - V_{OM}), R_T = 100 ohms	250	350	450	mV
ΔV_{OD}	Change in V_{OD} between high and low		—	—	50	mV
V_{OS}	Output voltage offset	(V_{OP} - V_{OM})/2, R_T = 100 ohms	1.125	1.25	1.375	V
ΔV_{OS}	Change in V_{OS} between H and L		—	—	50	mV
I_{OSD}	Output short circuit current	V_{OD} = 0V Driver outputs shorted	—	—	6	mA

LVPECL

The LatticeXP devices support differential LVPECL standard. This standard is emulated using complementary LVCMOS outputs in conjunction with a parallel resistor across the driver outputs. The LVPECL input standard is supported by the LVDS differential input buffer. The scheme shown in Figure 3-3 is one possible solution for point-to-point signals.

Figure 3-3. Differential LVPECL

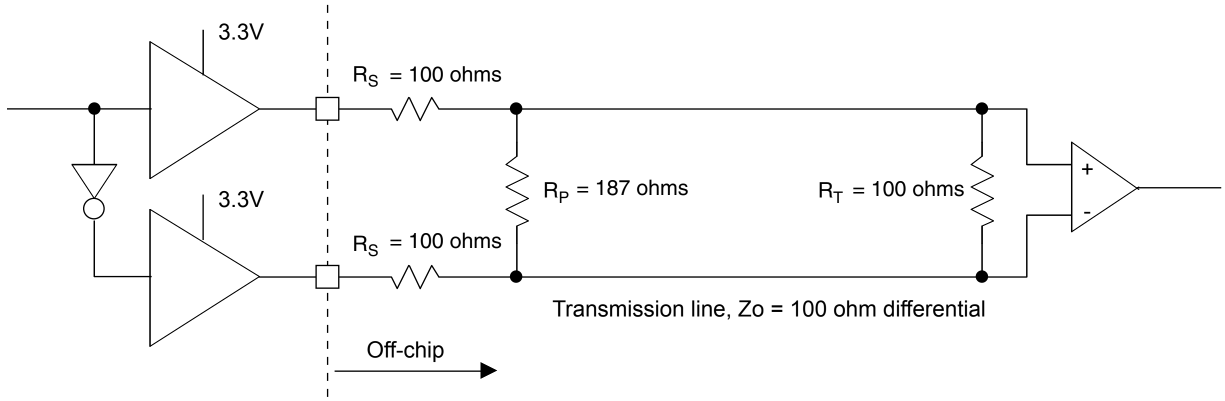


Table 3-3. LVPECL DC Conditions[1]

Over Recommended Operating Conditions

Symbol	Description	Typical	Units
Z_{OUT}	Output impedance	100	ohms
R_P	Driver parallel resistor	187	ohms
R_S	Driver series resistor	100	ohms
R_T	Receiver termination	100	ohms
V_{OH}	Output high voltage	2.03	V
V_{OL}	Output low voltage	1.27	V
V_{OD}	Output differential voltage	0.76	V
V_{CM}	Output common mode voltage	1.65	V
Z_{BACK}	Back impedance	85.7	ohms
I_{DC}	DC output current	12.7	mA

1. For input buffer, see LVDS table.

For further information on LVPECL, BLVDS and other differential interfaces please see details of additional technical documentation at the end of the data sheet.

RSDS

The LatticeXP devices support differential RSDS standard. This standard is emulated using complementary LVCMOS outputs in conjunction with a parallel resistor across the driver outputs. The RSDS input standard is supported by the LVDS differential input buffer. The scheme shown in Figure 3-4 is one possible solution for RSDS standard implementation. Use LVDS25E mode with suggested resistors for RSDS operation. Resistor values in Figure 3-4 are industry standard values for 1% resistors.

LatticeXP External Switching Characteristics

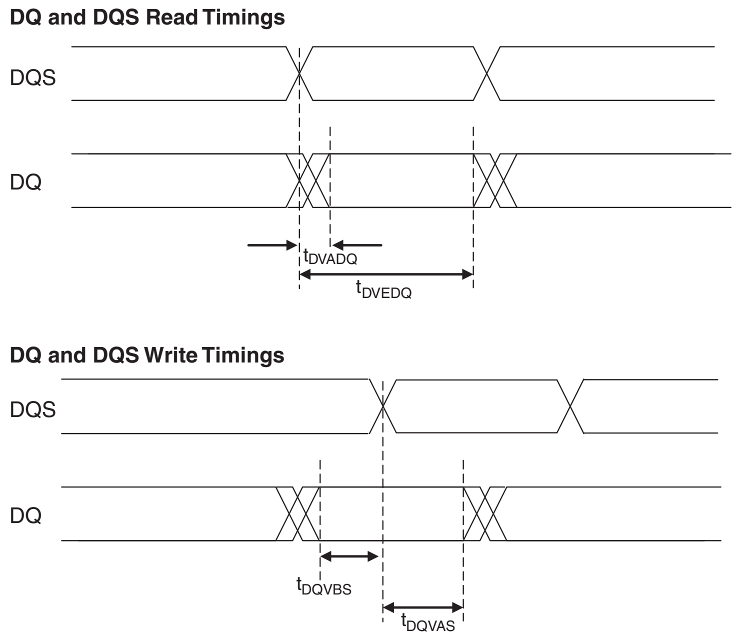
Over Recommended Operating Conditions

Parameter	Description	Device	-5		-4		-3		Units
			Min.	Max.	Min.	Max.	Min.	Max.	
General I/O Pin Parameters (Using Primary Clock without PLL)[1]									
t_{CO}	Clock to Output - PIO Output Register	LFXP3	—	5.12	—	6.12	—	7.43	ns
		LFXP6	—	5.30	—	6.34	—	7.69	ns
		LFXP10	—	5.52	—	6.60	—	8.00	ns
		LFXP15	—	5.72	—	6.84	—	8.29	ns
		LFXP20	—	5.97	—	7.14	—	8.65	ns
t_{SU}	Clock to Data Setup - PIO Input Register	LFXP3	-0.40	—	-0.28	—	-0.16	—	ns
		LFXP6	-0.33	—	-0.32	—	-0.30	—	ns
		LFXP10	-0.61	—	-0.71	—	-0.81	—	ns
		LFXP15	-0.71	—	-0.77	—	-0.87	—	ns
		LFXP20	-0.95	—	-1.14	—	-1.35	—	ns
t_H	Clock to Data Hold - PIO Input Register	LFXP3	2.10	—	2.50	—	2.98	—	ns
		LFXP6	2.28	—	2.72	—	3.24	—	ns
		LFXP10	3.02	—	3.51	—	3.71	—	ns
		LFXP15	2.70	—	3.22	—	3.85	—	ns
		LFXP20	2.95	—	3.52	—	4.21	—	ns
t_{SU_DEL}	Clock to Data Setup - PIO Input Register with Input Data Delay	LFXP3	2.38	—	2.49	—	2.66	—	ns
		LFXP6	2.92	—	3.18	—	3.42	—	ns
		LFXP10	2.72	—	2.75	—	2.84	—	ns
		LFXP15	2.99	—	3.13	—	3.18	—	ns
		LFXP20	4.47	—	4.56	—	4.80	—	ns
t_{H_DEL}	Clock to Data Hold - PIO Input Register with Input Data Delay	LFXP3	-0.70	—	-0.80	—	-0.92	—	ns
		LFXP6	-0.47	—	-0.38	—	-0.31	—	ns
		LFXP10	-0.60	—	-0.47	—	-0.32	—	ns
		LFXP15	-1.05	—	-0.98	—	-1.01	—	ns
		LFXP20	-0.80	—	-0.58	—	-0.31	—	ns
f_{MAX_IO}	Clock Frequency of I/O and PFU Register	All	—	400	—	360	—	320	MHz
DDR I/O Pin Parameters[2]									
t_{DVADQ}	Data Valid After DQS (DDR Read)	All	—	0.19	—	0.19	—	0.19	UI
t_{DVEDQ}	Data Hold After DQS (DDR Read)	All	0.67	—	0.67	—	0.67	—	UI
t_{DQVBS}	Data Valid Before DQS	All	0.20	—	0.20	—	0.20	—	UI
t_{DQVAS}	Data Valid After DQS	All	0.20	—	0.20	—	0.20	—	UI
f_{MAX_DDR}	DDR Clock Frequency	All	95	166	95	133	95	100	MHz
Primary and Secondary Clocks									
f_{MAX_PRI}	Frequency for Primary Clock Tree	All	—	450	—	412	—	375	MHz
t_{W_PRI}	Clock Pulse Width for Primary Clock	All	1.19	—	1.19	—	1.19	—	ns
t_{SKEW_PRI}	Primary Clock Skew within an I/O Bank	LFXP3/6/10/15	—	250	—	300	—	350	ps
		LFXP20	—	300	—	350	—	400	ps

1. General timing numbers based on LVCMOS 2.5, 12mA.
2. DDR timing numbers based on SSTL I/O.

Timing v.F0.11

Figure 3-5. DDR Timings



LatticeXP Family Timing Adders[1] (Continued)

Over Recommended Operating Conditions

Buffer Type	Description	-5	-4	-3	Units
HSTL15_I	HSTL_15 class I	0.2	0.2	0.2	ns
HSTL15_III	HSTL_15 class III	0.2	0.2	0.2	ns
HSTL15D_I	Differential HSTL 15 class I	0.2	0.2	0.2	ns
HSTL15D_III	Differential HSTL 15 class III	0.2	0.2	0.2	ns
SSTL33_I	SSTL_3 class I	0.1	0.1	0.1	ns
SSTL33_II	SSTL_3 class II	0.3	0.3	0.3	ns
SSTL33D_I	Differential SSTL_3 class I	0.1	0.1	0.1	ns
SSTL33D_II	Differential SSTL_3 class II	0.3	0.3	0.3	ns
SSTL25_I	SSTL_2 class I	-0.1	-0.1	-0.1	ns
SSTL25_II	SSTL_2 class II	0.3	0.3	0.3	ns
SSTL25D_I	Differential SSTL_2 class I	-0.1	-0.1	-0.1	ns
SSTL25D_II	Differential SSTL_2 class II	0.3	0.3	0.3	ns
SSTL18_I	SSTL_1.8 class I	0.1	0.1	0.1	ns
SSTL18D_I	Differential SSTL_1.8 class I	0.1	0.1	0.1	ns
LVTTL33_4mA	LVTTL 4mA drive	0.8	0.8	0.8	ns
LVTTL33_8mA	LVTTL 8mA drive	0.5	0.5	0.5	ns
LVTTL33_12mA	LVTTL 12mA drive	0.3	0.3	0.3	ns
LVTTL33_16mA	LVTTL 16mA drive	0.4	0.4	0.4	ns
LVTTL33_20mA	LVTTL 20mA drive	0.3	0.3	0.3	ns
LVCMOS33_2mA	LVCMOS 3.3 2mA drive	0.8	0.8	0.8	ns
LVCMOS33_4mA	LVCMOS 3.3 4mA drive	0.8	0.8	0.8	ns
LVCMOS33_8mA	LVCMOS 3.3 8mA drive	0.5	0.5	0.5	ns
LVCMOS33_12mA	LVCMOS 3.3 12mA drive	0.3	0.3	0.3	ns
LVCMOS33_16mA	LVCMOS 3.3 16mA drive	0.4	0.4	0.4	ns
LVCMOS33_20mA	LVCMOS 3.3 20mA drive	0.3	0.3	0.3	ns
LVCMOS25_2mA	LVCMOS 2.5 2mA drive	0.7	0.7	0.7	ns
LVCMOS25_4mA	LVCMOS 2.5 4mA drive	0.7	0.7	0.7	ns
LVCMOS25_8mA	LVCMOS 2.5 8mA drive	0.4	0.4	0.4	ns
LVCMOS25_12mA	LVCMOS 2.5 12mA drive	0.0	0.0	0.0	ns
LVCMOS25_16mA	LVCMOS 2.5 16mA drive	0.2	0.2	0.2	ns
LVCMOS25_20mA	LVCMOS 2.5 20mA drive	0.4	0.4	0.4	ns
LVCMOS18_2mA	LVCMOS 1.8 2mA drive	0.6	0.6	0.6	ns
LVCMOS18_4mA	LVCMOS 1.8 4mA drive	0.6	0.6	0.6	ns
LVCMOS18_8mA	LVCMOS 1.8 8mA drive	0.4	0.4	0.4	ns
LVCMOS18_12mA	LVCMOS 1.8 12mA drive	0.2	0.2	0.2	ns
LVCMOS18_16mA	LVCMOS 1.8 16mA drive	0.2	0.2	0.2	ns
LVCMOS15_2mA	LVCMOS 1.5 2mA drive	0.6	0.6	0.6	ns
LVCMOS15_4mA	LVCMOS 1.5 4mA drive	0.6	0.6	0.6	ns
LVCMOS15_8mA	LVCMOS 1.5 8mA drive	0.2	0.2	0.2	ns
LVCMOS12_2mA	LVCMOS 1.2 2mA drive	0.4	0.4	0.4	ns
LVCMOS12_6mA	LVCMOS 1.2 6mA drive	0.4	0.4	0.4	ns
PCI33	PCI33	0.3	0.3	0.3	ns

1. General timing numbers based on LVCMOS 2.5, 12mA.

Timing v.F0.11

LFXP3 & LFXP6 Logic Signal Connections: 208 PQFP (Cont.)

Pin Number	LFXP3				LFXP6			
	Pin Function	Bank	Differential	Dual Function	Pin Function	Bank	Differential	Dual Function
139	PR7A	2	T[3]	DQS	PR7A	2	T[3]	DQS
140	VCCIO2	2	-	-	VCCIO2	2	-	-
141	PR6B	2	-	VREF1_2	PR6B	2	-	VREF1_2
142	PR5A	2	-	VREF2_2	PR5A	2	-	VREF2_2
143	GNDIO2	2	-	-	GNDIO2	2	-	-
144	PR4B	2	C[3]	-	PR4B	2	C[3]	-
145	PR4A	2	T[3]	-	PR4A	2	T[3]	-
146	PR3B	2	C	RUM0_PLLC_FB_A	PR3B	2	C	RUM0_PLLC_FB_A
147	PR3A	2	T	RUM0_PLLT_FB_A	PR3A	2	T	RUM0_PLLT_FB_A
148	PR2B	2	C[3]	-	PR2B	2	C[3]	-
149	VCCIO2	2	-	-	VCCIO2	2	-	-
150	PR2A	2	T[3]	-	PR2A	2	T[3]	-
151	VCC	-	-	-	VCC	-	-	-
152	VCCAUX	-	-	-	VCCAUX	-	-	-
153	TDO	-	-	-	TDO	-	-	-
154	VCCJ	-	-	-	VCCJ	-	-	-
155	TDI	-	-	-	TDI	-	-	-
156	TMS	-	-	-	TMS	-	-	-
157	TCK	-	-	-	TCK	-	-	-
158	VCC	-	-	-	VCC	-	-	-
159	PT25A	1	-	VREF1_1	PT28A	1	-	VREF1_1
160	PT24B	1	C	-	PT27B	1	C	-
161	PT24A	1	T	-	PT27A	1	T	-
162	PT23A	1	-	D0	PT26A	1	-	D0
163	GNDIO1	1	-	-	GNDIO1	1	-	-
164	PT22B	1	C	D1	PT25B	1	C	D1
165	PT22A	1	T	VREF2_1	PT25A	1	T	VREF2_1
166	PT21A	1	-	D2	PT24A	1	-	D2
167	VCCIO1	1	-	-	VCCIO1	1	-	-
168	PT20B	1	C	D3	PT23B	1	C	D3
169	PT20A	1	T	-	PT23A	1	T	-
170	PT19B	1	C	-	PT22B	1	C	-
171	PT19A	1	T	DQS	PT22A	1	T	DQS
172	GNDIO1	1	-	-	GNDIO1	1	-	-
173	PT18B	1	-	-	PT21B	1	-	-
174	PT17A	1	-	D4	PT20A	1	-	D4
175	PT16B	1	C	-	PT19B	1	C	-
176	PT16A	1	T	D5	PT19A	1	T	D5
177	VCCIO1	1	-	-	VCCIO1	1	-	-
178	PT15B	1	C	D6	PT18B	1	C	D6
179	PT15A	1	T	-	PT18A	1	T	-
180	PT14B	1	-	D7	PT17B	1	-	D7
181	GND	-	-	-	GND	-	-	-
182	VCC	-	-	-	VCC	-	-	-
183	PT13B	0	C	BUSY	PT16B	0	C	BUSY
184	GNDIO0	0	-	-	GNDIO0	0	-	-

LFXP6 & LFXP10 Logic Signal Connections: 256 fpBGA (Cont.)

	LFXP6				LFXP10			
Ball Number	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
E16	TDO	-	-	-	TDO	-	-	-
D16	VCCJ	-	-	-	VCCJ	-	-	-
D14	TDI	-	-	-	TDI	-	-	-
C14	TMS	-	-	-	TMS	-	-	-
B14	TCK	-	-	-	TCK	-	-	-
-	GNDIO1	1	-	-	GNDIO1	1	-	-
A15	PT31B	1	C	-	PT35B	1	C	-
B15	PT31A	1	T	-	PT35A	1	T	-
-	GNDIO1	1	-	-	GNDIO1	1	-	-
D12	PT28A	1	-	VREF1_1	PT34B	1	C	VREF1_1
C11	PT30A	1	T	DQS	PT34A	1	T	DQS
A14	PT29B	1	-	-	PT33B	1	-	-
B13	PT30B	1	C	-	PT32A	1	-	-
F12	PT27B	1	C	-	PT31B	1	C	-
E11	PT27A	1	T	-	PT31A	1	T	-
A13	PT26B	1	C	-	PT30B	1	C	-
C13	PT26A	1	T	D0	PT30A	1	T	D0
-	GNDIO1	1	-	-	GNDIO1	1	-	-
C10	PT25B	1	C	D1	PT29B	1	C	D1
E10	PT25A	1	T	VREF2_1	PT29A	1	T	VREF2_1
A12	PT24B	1	C	-	PT28B	1	C	-
B12	PT24A	1	T	D2	PT28A	1	T	D2
C12	PT23B	1	C	D3	PT27B	1	C	D3
A11	PT23A	1	T	-	PT27A	1	T	-
B11	PT22B	1	C	-	PT26B	1	C	-
D11	PT22A	1	T	DQS	PT26A	1	T	DQS
-	GNDIO1	1	-	-	GNDIO1	1	-	-
B9	PT21B	1	-	-	PT25B	1	-	-
D9	PT20A	1	-	D4	PT24A	1	-	D4
A10	PT19B	1	C	-	PT23B	1	C	-
B10	PT19A	1	T	D5	PT23A	1	T	D5
D10	PT18B	1	C	D6	PT22B	1	C	D6
A9	PT18A	1	T	-	PT22A	1	T	-
C9	PT17B	1	C	D7	PT21B	1	C	D7
C8	PT17A	1	T	-	PT21A	1	T	-
E9	PT16B	0	C	BUSY	PT20B	0	C	BUSY
-	GNDIO0	0	-	-	GNDIO0	0	-	-
B8	PT16A	0	T	CS1N	PT20A	0	T	CS1N
A8	PT15B	0	C	PCLKC0_0	PT19B	0	C	PCLKC0_0
A7	PT15A	0	T	PCLKT0_0	PT19A	0	T	PCLKT0_0
B7	PT14B	0	C	-	PT18B	0	C	-
C7	PT14A	0	T	DQS	PT18A	0	T	DQS

LFXP15 & LFXP20 Logic Signal Connections: 256 fpBGA (Cont.)

	LFXP15				LFXP20			
Ball Number	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
L4	PL32A	6	-	-	PL36A	6	-	-
-	GNDIO6	6	-	-	GNDIO6	6	-	-
K4	PL33A	6	T	-	PL37A	6	T	-
K5	PL33B	6	C	-	PL37B	6	C	-
N1	PL35A	6	-	VREF2_6	PL39A	6	-	VREF2_6
N2	PL36B	6	-	-	PL40B	6	-	-
P1	PL37A	6	T[3]	DQS	PL41A	6	T[3]	DQS
P2	PL37B	6	C[3]	-	PL41B	6	C[3]	-
-	GNDIO6	6	-	-	GNDIO6	6	-	-
L5	PL38A	6	T	LLM0_PLLT_FB_A	PL42A	6	T	LLM0_PLLT_FB_A
M6	PL38B	6	C	LLM0_PLLC_FB_A	PL42B	6	C	LLM0_PLLC_FB_A
M3	PL39A	6	T[3]	-	PL43A	6	T[3]	-
N3	PL39B	6	C[3]	-	PL43B	6	C[3]	-
-	GNDIO6	6	-	-	GNDIO6	6	-	-
P4	SLEEPN[1]/TOE[2]	-	-	-	SLEEPN[1]/TOE[2]	-	-	-
P3	INITN	5	-	-	INITN	5	-	-
-	GNDIO5	5	-	-	GNDIO5	5	-	-
-	GNDIO5	5	-	-	GNDIO5	5	-	-
-	GNDIO5	5	-	-	GNDIO5	5	-	-
R4	PB11A	5	T	-	PB15A	5	T	-
N5	PB11B	5	C	-	PB15B	5	C	-
P5	PB12A	5	T	VREF1_5	PB16A	5	T	VREF1_5
-	GNDIO5	5	-	-	GNDIO5	5	-	-
R1	PB12B	5	C	-	PB16B	5	C	-
N6	PB13A	5	-	-	PB17A	5	-	-
M7	PB14B	5	-	-	PB18B	5	-	-
R2	PB15A	5	T	DQS	PB19A	5	T	DQS
T2	PB15B	5	C	-	PB19B	5	C	-
R3	PB16A	5	T	-	PB20A	5	T	-
T3	PB16B	5	C	-	PB20B	5	C	-
T4	PB17A	5	T	-	PB21A	5	T	-
R5	PB17B	5	C	VREF2_5	PB21B	5	C	VREF2_5
N7	PB18A	5	T	-	PB22A	5	T	-
-	GNDIO5	5	-	-	GNDIO5	5	-	-
M8	PB18B	5	C	-	PB22B	5	C	-
T5	PB19A	5	T	-	PB23A	5	T	-
P6	PB19B	5	C	-	PB23B	5	C	-
T6	PB20A	5	T	-	PB24A	5	T	-
R6	PB20B	5	C	-	PB24B	5	C	-
P7	PB21A	5	-	-	PB25A	5	-	-
N8	PB22B	5	-	-	PB26B	5	-	-
R7	PB23A	5	T	DQS	PB27A	5	T	DQS

LFXP15 & LFXP20 Logic Signal Connections: 256 fpBGA (Cont.)

	LFXP15				LFXP20			
Ball Number	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
G10	GND	-	-	-	GND	-	-	-
G7	GND	-	-	-	GND	-	-	-
G8	GND	-	-	-	GND	-	-	-
G9	GND	-	-	-	GND	-	-	-
H10	GND	-	-	-	GND	-	-	-
H7	GND	-	-	-	GND	-	-	-
H8	GND	-	-	-	GND	-	-	-
H9	GND	-	-	-	GND	-	-	-
J10	GND	-	-	-	GND	-	-	-
J7	GND	-	-	-	GND	-	-	-
J8	GND	-	-	-	GND	-	-	-
J9	GND	-	-	-	GND	-	-	-
K10	GND	-	-	-	GND	-	-	-
K7	GND	-	-	-	GND	-	-	-
K8	GND	-	-	-	GND	-	-	-
K9	GND	-	-	-	GND	-	-	-
L11	GND	-	-	-	GND	-	-	-
L6	GND	-	-	-	GND	-	-	-
T1	GND	-	-	-	GND	-	-	-
T16	GND	-	-	-	GND	-	-	-
D13	VCC	-	-	-	VCC	-	-	-
D4	VCC	-	-	-	VCC	-	-	-
E12	VCC	-	-	-	VCC	-	-	-
E5	VCC	-	-	-	VCC	-	-	-
M12	VCC	-	-	-	VCC	-	-	-
M5	VCC	-	-	-	VCC	-	-	-
N13	VCC	-	-	-	VCC	-	-	-
N4	VCC	-	-	-	VCC	-	-	-
E13	VCCAUX	-	-	-	VCCAUX	-	-	-
E4	VCCAUX	-	-	-	VCCAUX	-	-	-
M13	VCCAUX	-	-	-	VCCAUX	-	-	-
M4	VCCAUX	-	-	-	VCCAUX	-	-	-
F7	VCCIO0	0	-	-	VCCIO0	0	-	-
F8	VCCIO0	0	-	-	VCCIO0	0	-	-
F10	VCCIO1	1	-	-	VCCIO1	1	-	-
F9	VCCIO1	1	-	-	VCCIO1	1	-	-
G11	VCCIO2	2	-	-	VCCIO2	2	-	-
H11	VCCIO2	2	-	-	VCCIO2	2	-	-
J11	VCCIO3	3	-	-	VCCIO3	3	-	-
K11	VCCIO3	3	-	-	VCCIO3	3	-	-
L10	VCCIO4	4	-	-	VCCIO4	4	-	-
L9	VCCIO4	4	-	-	VCCIO4	4	-	-

LFXP10, LFXP15 & LFXP20 Logic Signal Connections: 388 fpBGA (Cont.)

	LFXP10				LFXP15				LFXP20			
Ball Number	Ball Function	Bank	Diff.	Dual Function	Ball Function	Bank	Diff.	Dual Function	Ball Function	Bank	Diff.	Dual Function
M21	VCCP1	-	-	-	VCCP1	-	-	-	VCCP1	-	-	-
-	GNDIO2	2	-	-	GNDIO2	2	-	-	GNDIO2	2	-	-
M22	PR18B	2	C3	-	PR22B	2	C3	-	PR22B	2	C3	-
L22	PR18A	2	T3	-	PR22A	2	T3	-	PR22A	2	T3	-
K22	PR17B	2	C	PCLKC2_0	PR21B	2	C	PCLKC2_0	PR21B	2	C	PCLKC2_0
K21	PR17A	2	T	PCLKT2_0	PR21A	2	T	PCLKT2_0	PR21A	2	T	PCLKT2_0
L19	PR16B	2	C3	-	PR20B	2	C3	-	PR20B	2	C3	-
K20	PR16A	2	T3	DQS	PR20A	2	T3	DQS	PR20A	2	T3	DQS
L20	PR15B	2	-	-	PR19B	2	-	-	PR19B	2	-	-
L21	PR14A	2	-	VREF1_2	PR18A	2	-	VREF1_2	PR18A	2	-	VREF1_2
-	GNDIO2	2	-	-	GNDIO2	2	-	-	GNDIO2	2	-	-
J22	PR13B	2	C3	-	PR17B	2	C3	-	PR17B	2	C3	-
J21	PR13A	2	T3	-	PR17A	2	T3	-	PR17A	2	T3	-
H22	PR12B	2	C	RUM0_PLLC_IN_A	PR16B	2	C	RUM0_PLLC_IN_A	PR16B	2	C	RUM0_PLLC_IN_A
H21	PR12A	2	T	RUM0_PLLT_IN_A	PR16A	2	T	RUM0_PLLT_IN_A	PR16A	2	T	RUM0_PLLT_IN_A
K19	PR11B	2	C3	-	PR15B	2	C3	-	PR15B	2	C3	-
J19	PR11A	2	T3	-	PR15A	2	T3	-	PR15A	2	T3	-
-	GNDIO2	2	-	-	GNDIO2	2	-	-	GNDIO2	2	-	-
J20	PR9B	2	C3	-	PR13B	2	C3	-	PR13B	2	C3	-
H20	PR9A	2	T3	-	PR13A	2	T3	-	PR13A	2	T3	-
H19	PR8B	2	C	-	PR12B	2	C	-	PR12B	2	C	-
G19	PR8A	2	T	-	PR12A	2	T	-	PR12A	2	T	-
G22	PR7B	2	C3	-	PR11B	2	C3	-	PR11B	2	C3	-
G21	PR7A	2	T3	DQS	PR11A	2	T3	DQS	PR11A	2	T3	DQS
-	GNDIO2	2	-	-	GNDIO2	2	-	-	GNDIO2	2	-	-
F20	PR6B	2	-	-	PR10B	2	-	-	PR10B	2	-	-
G20	PR5A	2	-	VREF2_2	PR9A	2	-	VREF2_2	PR9A	2	-	VREF2_2
F22	PR4B	2	C3	-	PR8B	2	C3	-	PR8B	2	C3	-
F21	PR4A	2	T3	-	PR8A	2	T3	-	PR8A	2	T3	-
E22	PR3B	2	C	RUM0_PLLC_FB_A	PR7B	2	C	RUM0_PLLC_FB_A	PR7B	2	C	RUM0_PLLC_FB_A
E21	PR3A	2	T	RUM0_PLLT_FB_A	PR7A	2	T	RUM0_PLLT_FB_A	PR7A	2	T	RUM0_PLLT_FB_A
D22	PR2B	2	C3	-	PR6B	2	C3	-	PR6B	2	C3	-
D21	PR2A	2	T3	-	PR6A	2	T3	-	PR6A	2	T3	-
-	GNDIO2	2	-	-	GNDIO2	2	-	-	GNDIO2	2	-	-
F19	TDO	-	-	-	TDO	-	-	-	TDO	-	-	-
E20	VCCJ	-	-	-	VCCJ	-	-	-	VCCJ	-	-	-
D20	TDI	-	-	-	TDI	-	-	-	TDI	-	-	-
D19	TMS	-	-	-	TMS	-	-	-	TMS	-	-	-
D18	TCK	-	-	-	TCK	-	-	-	TCK	-	-	-
-	GNDIO1	1	-	-	GNDIO1	1	-	-	GNDIO1	1	-	-
E19	-	-	-	-	PT48A	1	-	-	PT52A	1	-	-
D17	-	-	-	-	PT47B	1	C	-	PT51B	1	C	-
D16	-	-	-	-	PT47A	1	T	DQS	PT51A	1	T	DQS
C16	-	-	-	-	PT46B	1	-	-	PT50B	1	-	-
C15	-	-	-	-	PT45A	1	-	-	PT49A	1	-	-
C17	-	-	-	-	PT44B	1	C	-	PT48B	1	C	-
C18	PT39A	1	-	-	PT44A	1	T	-	PT48A	1	T	-
C19	PT38B	1	C	-	PT43B	1	C	-	PT47B	1	C	-
-	GNDIO1	1	-	-	GNDIO1	1	-	-	GNDIO1	1	-	-

LFXP15 & LFXP20 Logic Signal Connections: 484 fpBGA (Cont.)

	LFXP15				LFXP20			
Ball Number	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
T6	PL41A	6	T	-	PL45A	6	T	-
T5	PL41B	6	C	-	PL45B	6	C	-
-	GNDIO6	6	-	-	GNDIO6	6	-	-
U3	PL42A	6	T[3]	-	PL46A	6	T[3]	-
U4	PL42B	6	C[3]	-	PL46B	6	C[3]	-
V4	PL43A	6	-	-	PL47A	6	-	-
W4	SLEEPN[1]/ TOE[2]	-	-	-	SLEEPN[1]/ TOE[2]	-	-	-
W5	INITN	5	-	-	INITN	5	-	-
Y3	-	-	-	-	PB3B	5	-	-
-	GNDIO5	5	-	-	GNDIO5	5	-	-
U5	-	-	-	-	PB4A	5	T	-
V5	-	-	-	-	PB4B	5	C	-
Y4	-	-	-	-	PB5A	5	T	-
Y5	-	-	-	-	PB5B	5	C	-
V6	-	-	-	-	PB6A	5	T	-
-	GNDIO5	5	-	-	GNDIO5	5	-	-
U6	-	-	-	-	PB6B	5	C	-
W6	PB3A	5	T	-	PB7A	5	T	-
Y6	PB3B	5	C	-	PB7B	5	C	-
AA2	PB4A	5	T	-	PB8A	5	T	-
AA3	PB4B	5	C	-	PB8B	5	C	-
V7	PB5A	5	-	-	PB9A	5	-	-
U7	PB6B	5	-	-	PB10B	5	-	-
Y7	PB7A	5	T	DQS	PB11A	5	T	DQS
W7	PB7B	5	C	-	PB11B	5	C	-
AA4	PB8A	5	T	-	PB12A	5	T	-
-	GNDIO5	5	-	-	GNDIO5	5	-	-
AA5	PB8B	5	C	-	PB12B	5	C	-
AB3	PB9A	5	T	-	PB13A	5	T	-
AB4	PB9B	5	C	-	PB13B	5	C	-
AA6	PB10A	5	T	-	PB14A	5	T	-
AA7	PB10B	5	C	-	PB14B	5	C	-
U8	PB11A	5	T	-	PB15A	5	T	-
V8	PB11B	5	C	-	PB15B	5	C	-
Y8	PB12A	5	T	VREF1_5	PB16A	5	T	VREF1_5
-	GNDIO5	5	-	-	GNDIO5	5	-	-
W8	PB12B	5	C	-	PB16B	5	C	-
V9	PB13A	5	-	-	PB17A	5	-	-
U9	PB14B	5	-	-	PB18B	5	-	-
Y9	PB15A	5	T	DQS	PB19A	5	T	DQS
W9	PB15B	5	C	-	PB19B	5	C	-

LFXP15 & LFXP20 Logic Signal Connections: 484 fpBGA (Cont.)

	LFXP15				LFXP20			
Ball Number	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
B3	PT8B	0	C	-	PT12B	0	C	-
A3	PT8A	0	T	-	PT12A	0	T	-
-	GNDIO0	0	-	-	GNDIO0	0	-	-
D7	PT7B	0	C	-	PT11B	0	C	-
C7	PT7A	0	T	DQS	PT11A	0	T	DQS
B2	PT6B	0	-	-	PT10B	0	-	-
C2	PT5A	0	-	-	PT9A	0	-	-
C3	PT4B	0	C	-	PT8B	0	C	-
D3	PT4A	0	T	-	PT8A	0	T	-
F7	PT3B	0	C	-	PT7B	0	C	-
E7	PT3A	0	T	-	PT7A	0	T	-
-	GNDIO0	0	-	-	GNDIO0	0	-	-
C6	-	-	-	-	PT6B	0	C	-
D6	-	-	-	-	PT6A	0	T	-
C5	-	-	-	-	PT5B	0	C	-
C4	-	-	-	-	PT5A	0	T	-
F6	-	-	-	-	PT4B	0	C	-
E6	-	-	-	-	PT4A	0	T	-
-	GNDIO0	0	-	-	GNDIO0	0	-	-
E4	-	-	-	-	PT3B	0	-	-
E5	CFG0	0	-	-	CFG0	0	-	-
D4	CFG1	0	-	-	CFG1	0	-	-
D5	DONE	0	-	-	DONE	0	-	-
A1	GND	-	-	-	GND	-	-	-
A2	GND	-	-	-	GND	-	-	-
A21	GND	-	-	-	GND	-	-	-
A22	GND	-	-	-	GND	-	-	-
AA1	GND	-	-	-	GND	-	-	-
AA22	GND	-	-	-	GND	-	-	-
AB1	GND	-	-	-	GND	-	-	-
AB2	GND	-	-	-	GND	-	-	-
AB21	GND	-	-	-	GND	-	-	-
AB22	GND	-	-	-	GND	-	-	-
B1	GND	-	-	-	GND	-	-	-
B22	GND	-	-	-	GND	-	-	-
H14	GND	-	-	-	GND	-	-	-
H9	GND	-	-	-	GND	-	-	-
J10	GND	-	-	-	GND	-	-	-
J11	GND	-	-	-	GND	-	-	-
J12	GND	-	-	-	GND	-	-	-
J13	GND	-	-	-	GND	-	-	-
J14	GND	-	-	-	GND	-	-	-

Thermal Management

Thermal management is recommended as part of any sound FPGA design methodology. To assess the thermal characteristics of a system, Lattice specifies a maximum allowable junction temperature in all device data sheets. Designers must complete a thermal analysis of their specific design to ensure that the device and package do not exceed the junction temperature limits. Refer to the Thermal Management document to find the device/package specific thermal values.

For Further Information

For further information regarding Thermal Management, refer to the following located on the Lattice website at www.latticesemi.com.

- Thermal Management document
- Technical Note TN1052 - Power Estimation and Management for LatticeECP/EC and LatticeXP Devices
- Power Calculator tool included with Lattice's ispLEVER design tool, or as a standalone download from www.latticesemi.com/software